

HVU145

Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0437-0200 (Previous: ADE-208-1508A) Rev.2.00 Dec 07, 2004

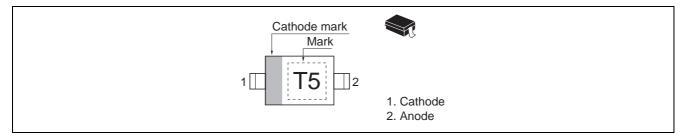
Features

- An optimal solution for antenna switching in mobile phones.
- Low capacitance. (C =0.45 pF max)
- Low forward resistance. (rf = $1.8 \Omega \text{ max}$)
- <u>Ultra small Resin Package (URP) is suitable for surface mount design.</u>

Ordering Information

Type No.	Laser Mark	Package Code
HVU145	T5	URP

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$	
Item	Symbol	Value	Unit	
Reverse voltage	V _R	60	V	
Forward current	IF	50	mA	
Power dissipation	Pd	150	mW	
Junction temperature	Тј	125	٥C	
Storage temperature	Tstg	-55 to +125	٥C	

Electrical Characteristics

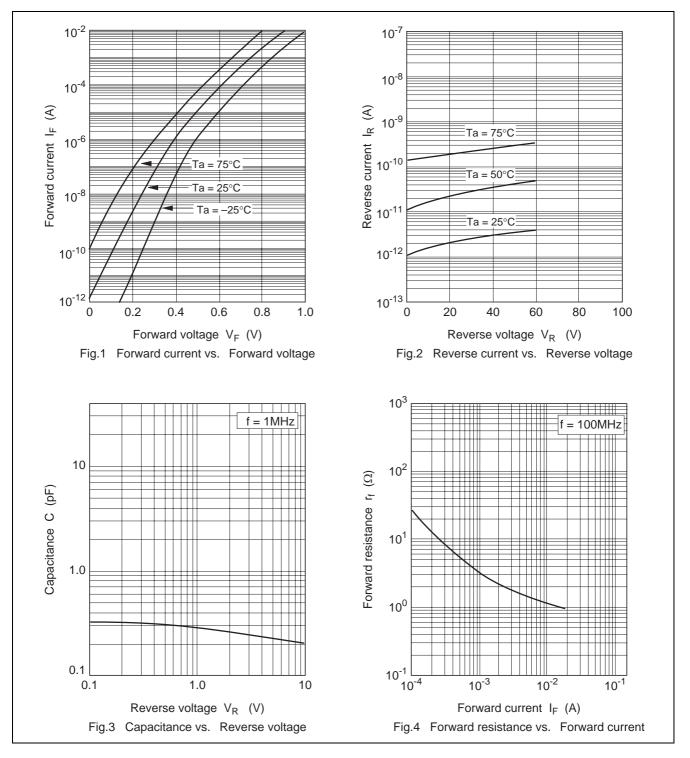
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	—		100	nA	V _R = 60 V
Forward voltage	V _F	—		0.9	V	$I_F = 2 \text{ mA}$
Capacitance	С	_	_	0.45	pF	$V_{R} = 1 V, f = 1 MHz$
Forward resistance	r _f	_	_	1.8	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability *1	—	100	_	_	V	$C = 200 \text{ pF}, R = 0 \Omega$, Both forward
						and reverse direction 1 pulse.

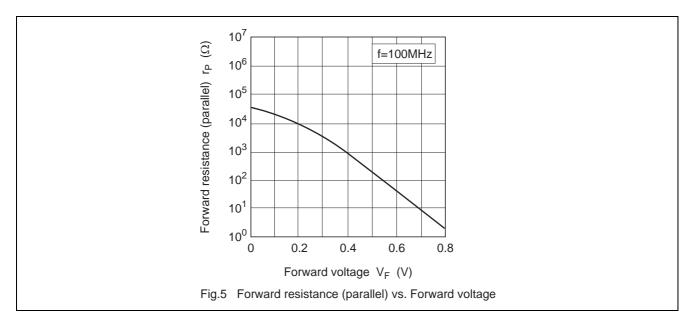
Note: 1. Failure criterion ; $I_R > 100$ nA at $V_R = 60$ V



Main Characteristic

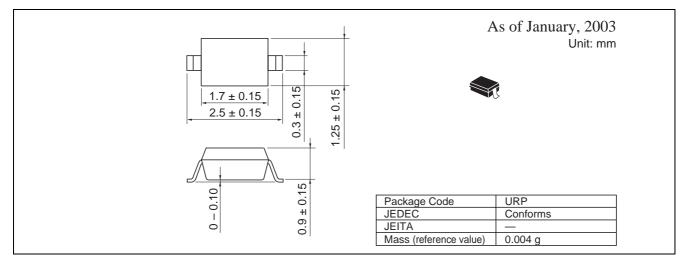








Package Dimensions





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